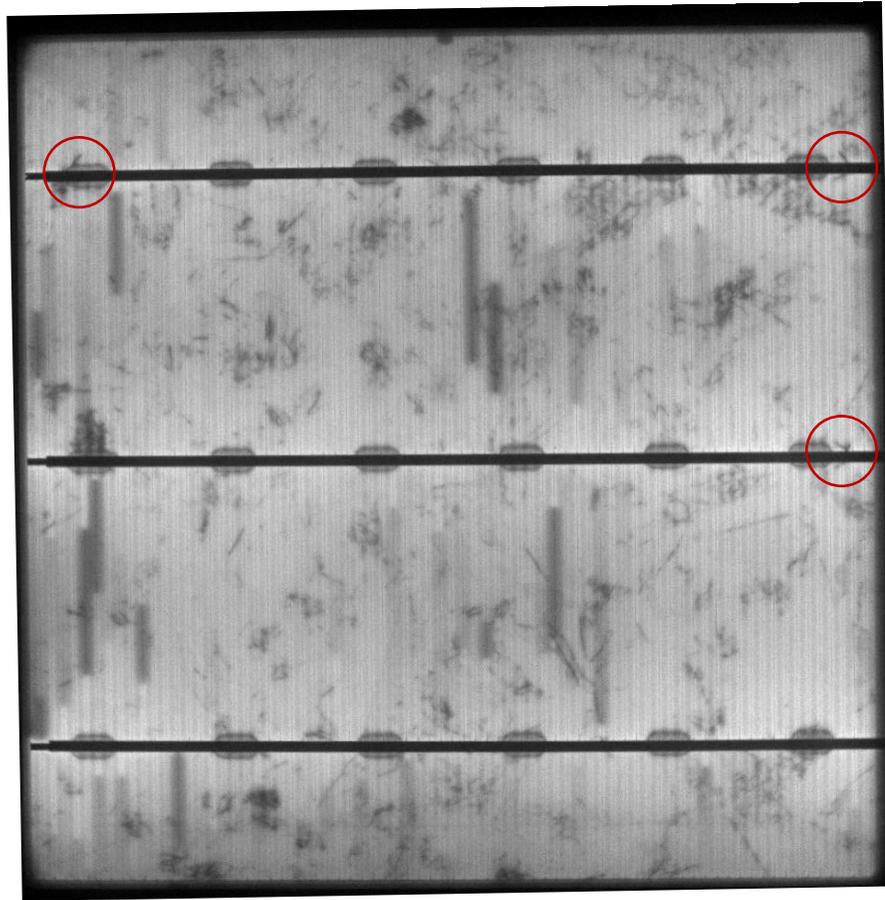


Stress measurements in Silicon solar cell interconnect ribbons using X-ray diffraction

A. Morlier, J. Käsewieter, F. Haase

Influence of cell interconnect ribbon stress on solar cell cracking?

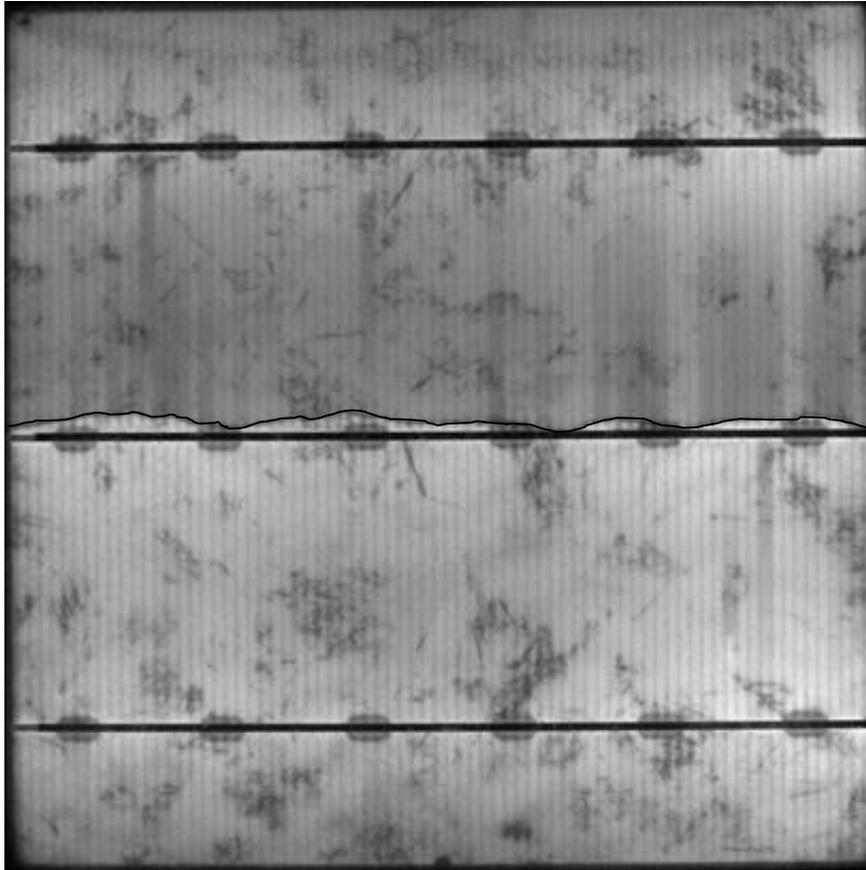


- Cracks in solar cells lead to power losses by insulating parts of the cells^{1,2}
- Cracks along the busbars and cell interconnect ribbons (CIR) potentially insulate a large area^{1,2}

¹ M. Köntges, I. Kunze, S. Kajari-Schröder, X. Breitenmoser, B. Bjørneklett, Sol. Energy Mater. Sol. Cells, 95 (2011), p.1131

² M. Sander, S. Dietrich, M. Pander, M. Ebert, S. Thormann, J. Wendt, J. Bagdahn, 27th European Photovoltaic Solar Energy Conference Frankfurt, Germany (2012), p. 3188

Influence of cell interconnect ribbon stress on solar cell cracking?

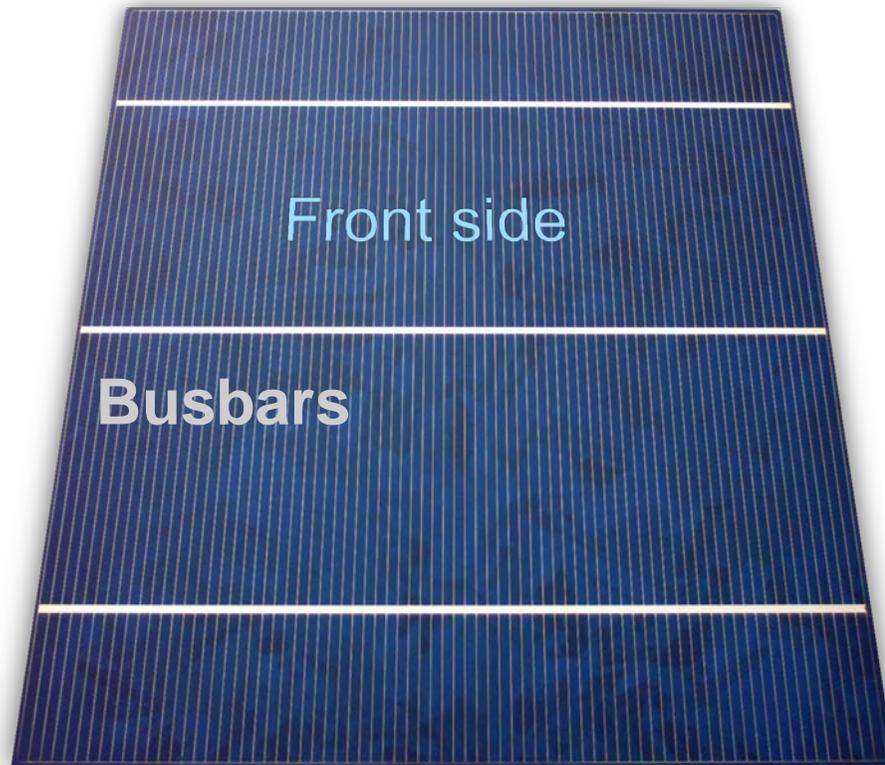
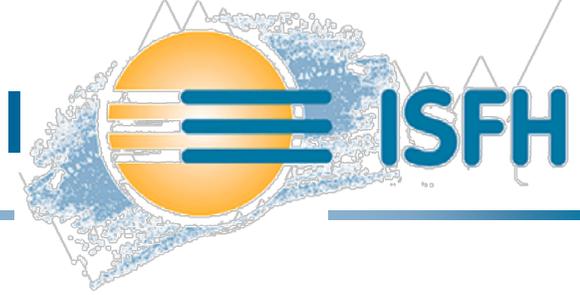


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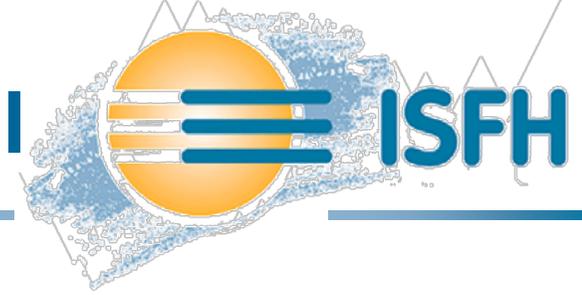
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Standard screen printed solar cell

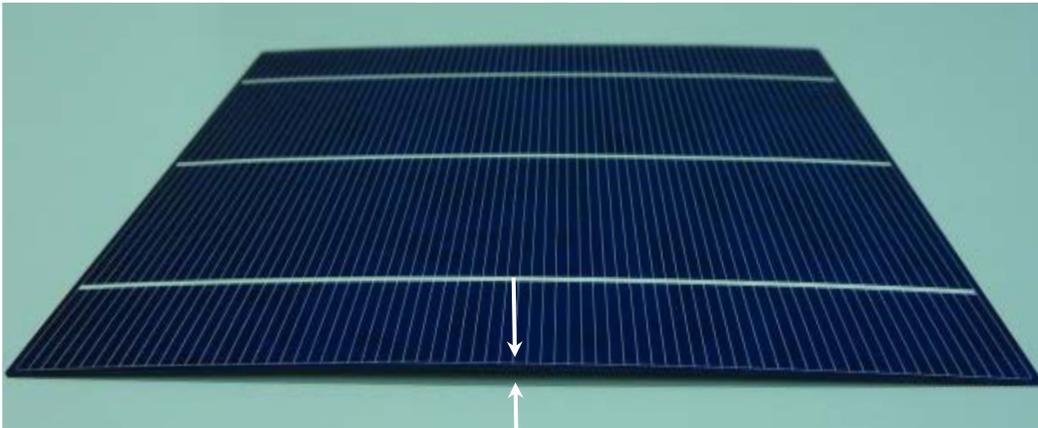


- 3 Ag busbars at front side as soldering contact

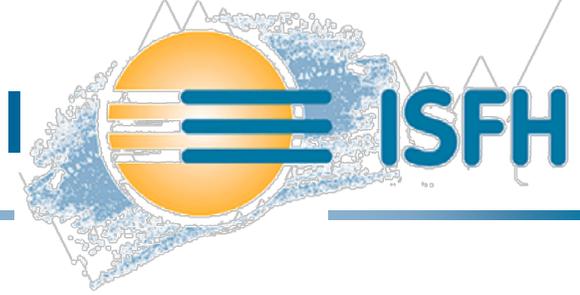
Standard screen printed solar cell



- 3 Ag busbars at front side as soldering contact
- Initial bow of about 2.1 mm



Standard screen printed solar cell

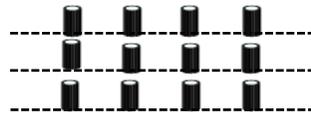


- 3 Ag busbars at front side as soldering contact
- Initial bow of about 2.1 mm
- 3 rows each with 6 silver pads at rear side as soldering contact

Soldering process



3 rows each with
10 soldering heads



Soldering belt with various heating zones

~80 °C

~240 °C

~180 °C

~20 °C

11
102
1004

Leibniz
Universität
Hannover

Soldering process



- CIR positioning

3 rows each with
10 soldering heads



Soldering belt with various heating zones

~80 °C

~240 °C

~180 °C

~20 °C

Soldering process



- CIR positioning
- Belt moving

3 rows each with
10 soldering heads



Soldering belt with various heating zones

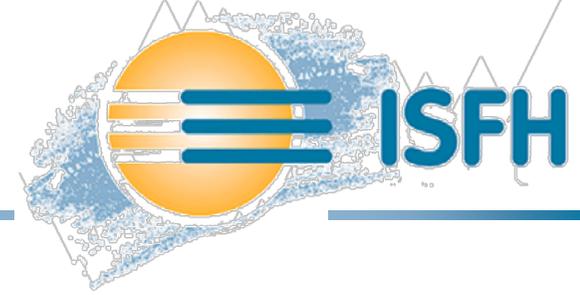
~80 °C

~240 °C

~180 °C

~20 °C

Soldering process



- CIR positioning
- Belt moving
- Solar cell positioning

3 rows each with
10 soldering heads



Soldering belt with various heating zones

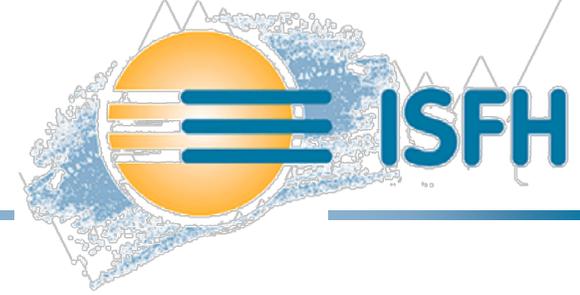
~80 °C

~240 °C

~180 °C

~20 °C

Soldering process



- CIR positioning
- Belt moving
- Solar cell positioning
- CIR positioning

3 rows each with
10 soldering heads



Soldering belt with various heating zones

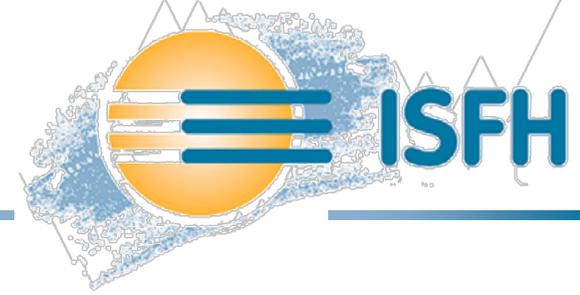
~80 °C

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Soldering process



- CIR positioning
- Belt moving
- Solar cell positioning
- CIR positioning
- Belt moving

3 rows each with
10 soldering heads



Soldering belt with various heating zones

~80 °C

~240 °C

~180 °C

~20 °C

Soldering process



3 rows each with
10 soldering heads

- CIR positioning
- Belt moving
- Solar cell positioning
- CIR positioning
- Belt moving
- Flattening and soldering



Soldering belt with various heating zones

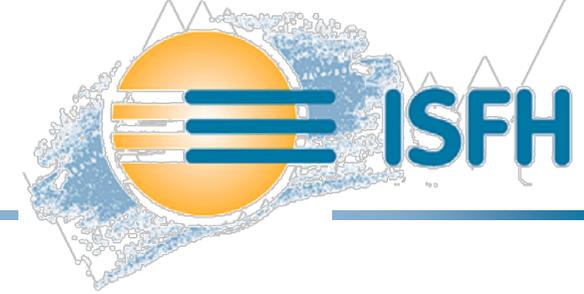
~80 °C

~240 °C

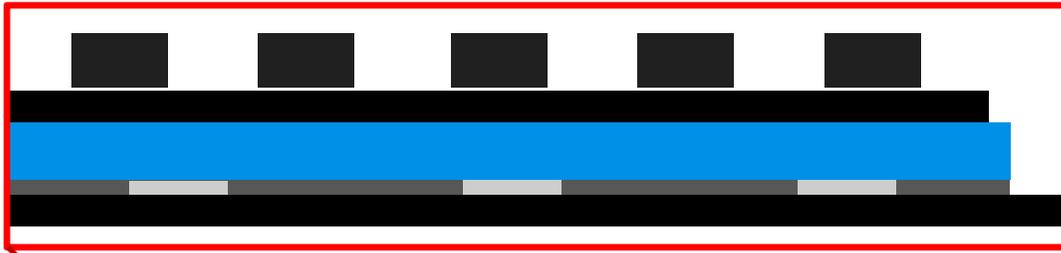
~180 °C

~20 °C

Soldering process

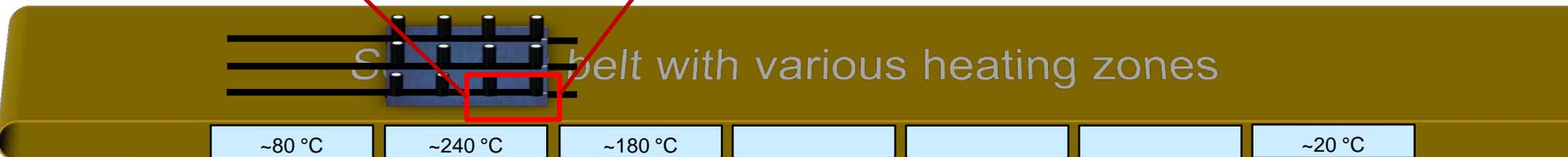


Cross section



3 rows each with
10 soldering heads

- CIR positioning
- Belt moving
- Solar cell positioning
- CIR positioning
- Belt moving
- Flattening and soldering



Soldering process



- CIR positioning
- Belt moving
- Solar cell positioning
- CIR positioning
- Belt moving
- Flattening and soldering

3 rows each with
10 soldering heads



Soldering belt with various heating zones

~80 °C

~240 °C

~180 °C

~20 °C

Soldering process



3 rows each with
10 soldering heads



- CIR positioning
- Belt moving
- Solar cell positioning
- CIR positioning
- Belt moving
- Flattening and soldering



belt with various heating zones

~80 °C

~240 °C

~180 °C

~20 °C

Stress estimation in CIR due to soldering process



- Solder solidifies at about 180 °C → CIR connects to initially bowed solar cell



Stress estimation in CIR due to soldering process

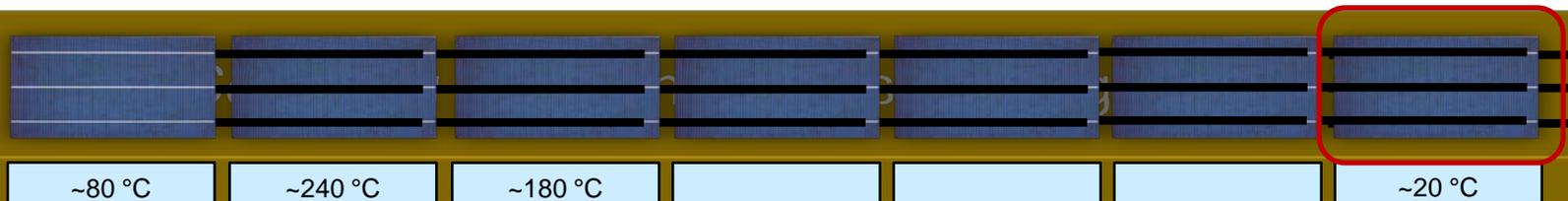


Assumptions:

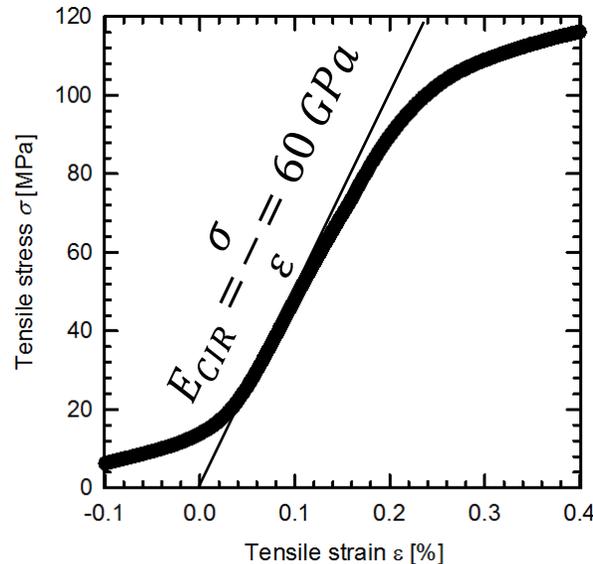
1. Coefficients of thermal expansion [10^{-6} K^{-1}]
 $\alpha_{\text{Cu}} = 16.5$ $\alpha_{\text{Si}} = 2.6$ $(\alpha_{\text{Cu}} - \alpha_{\text{Si}}) = 13.9$
2. Silicon dominates thermal shrinking

$$\varepsilon = 0.22\%$$

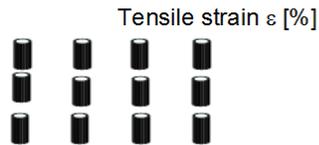
- Solder solidifies at about $180 \text{ }^\circ\text{C}$ \rightarrow CIR connects to initially bowed solar cell
- Thermal shrinking during cool down



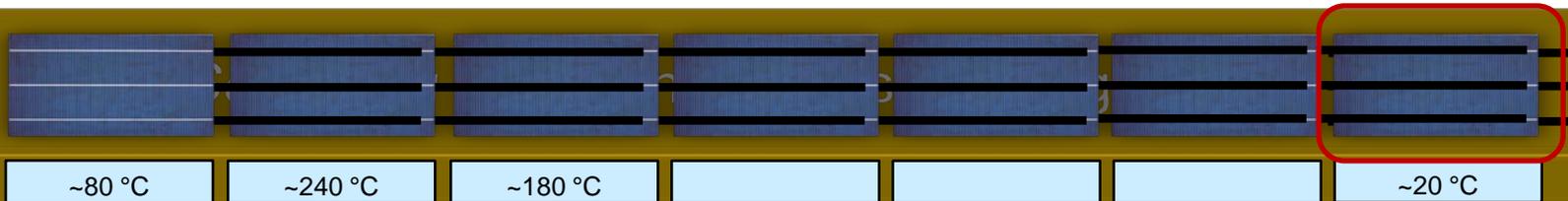
Tensile test of CIR



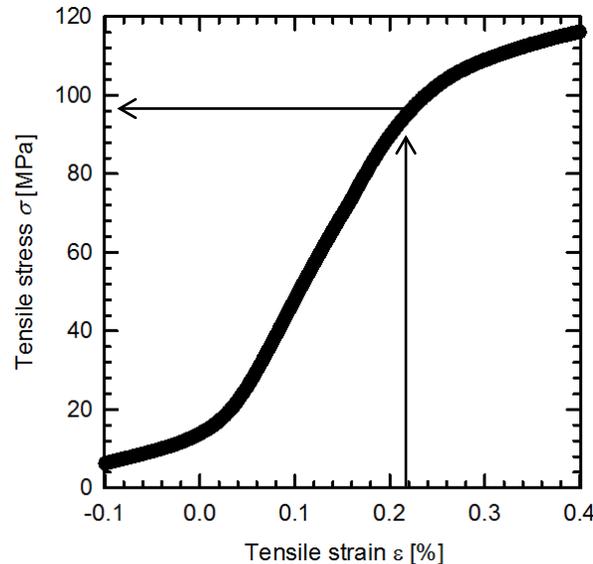
$\epsilon = 0.22\%$



- Solder solidifies at about 180 °C → CIR connects to initially bowed solar cell
- Thermal shrinking during cool down

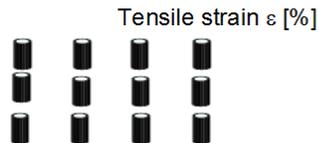


Stress in CIR



$\epsilon = 0.22\%$

$\sigma = 96 \text{ MPa}$



- Solder solidifies at about 180 °C → CIR connects to initially bowed solar cell
- Thermal shrinking during cool down



Influence of solder on stress



$$\begin{aligned}\epsilon_{yield_solder} &= \frac{\text{Yield stress}}{\text{Young's modulus}} \\ &= \frac{43 \text{ MPa}}{18 \text{ GPa}} = 0.24\%\end{aligned}$$

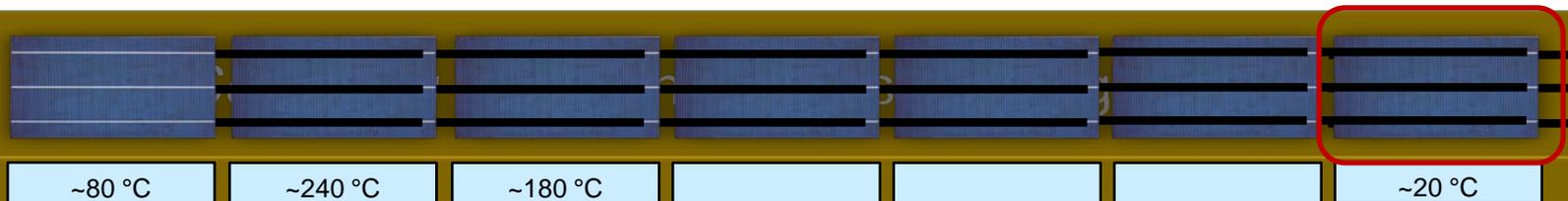
T. Siewert, S. Liu, D. R. Smith, J. C. Madeni;
Database for solder properties with
emphasis on new lead-free solders; NIST &
Colorado School of Mines

$$\epsilon = 0.22\%$$

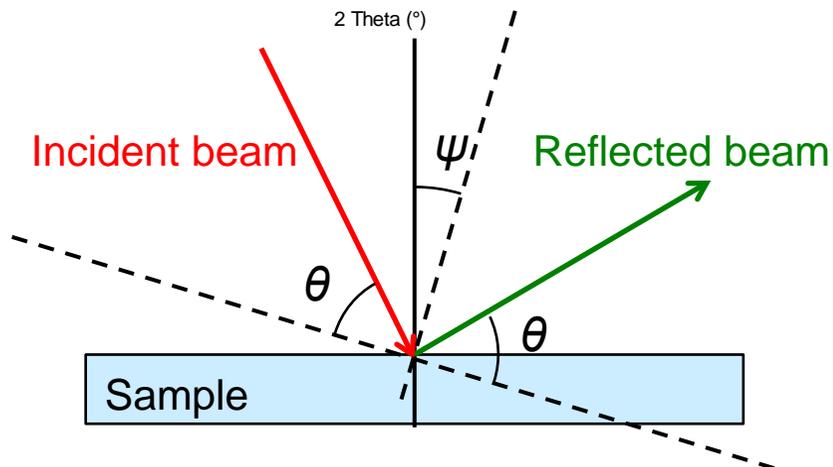
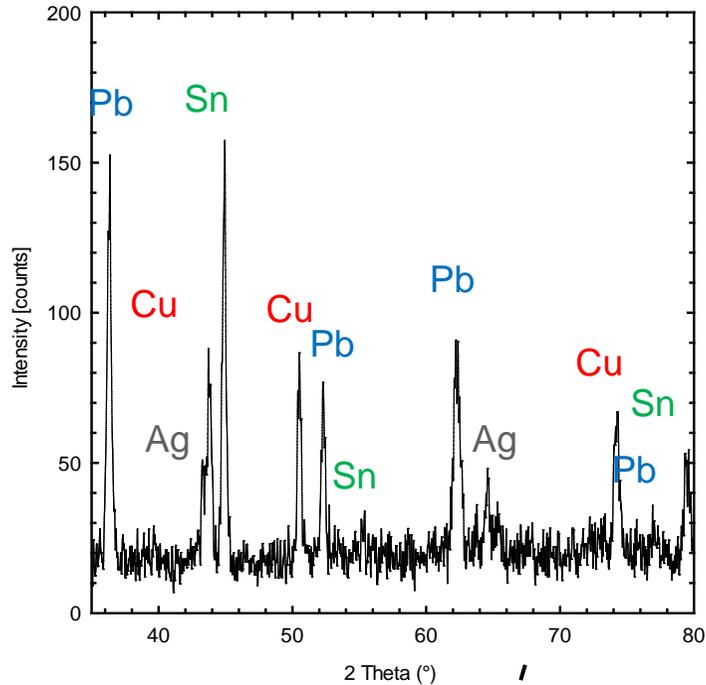
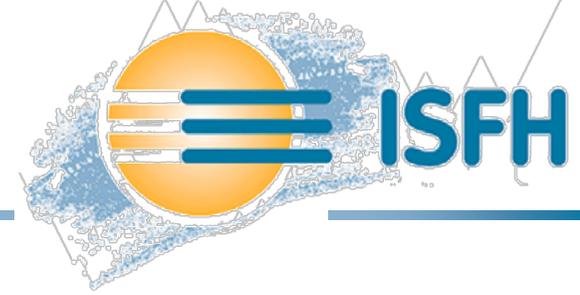
$$\sigma = 96 \text{ MPa}$$



- Solder solidifies at about 180 °C → CIR connects to initially bowed solar cell
- Thermal shrinking during cool down
- Exceeding of solder yield strain? → No CIR relaxation



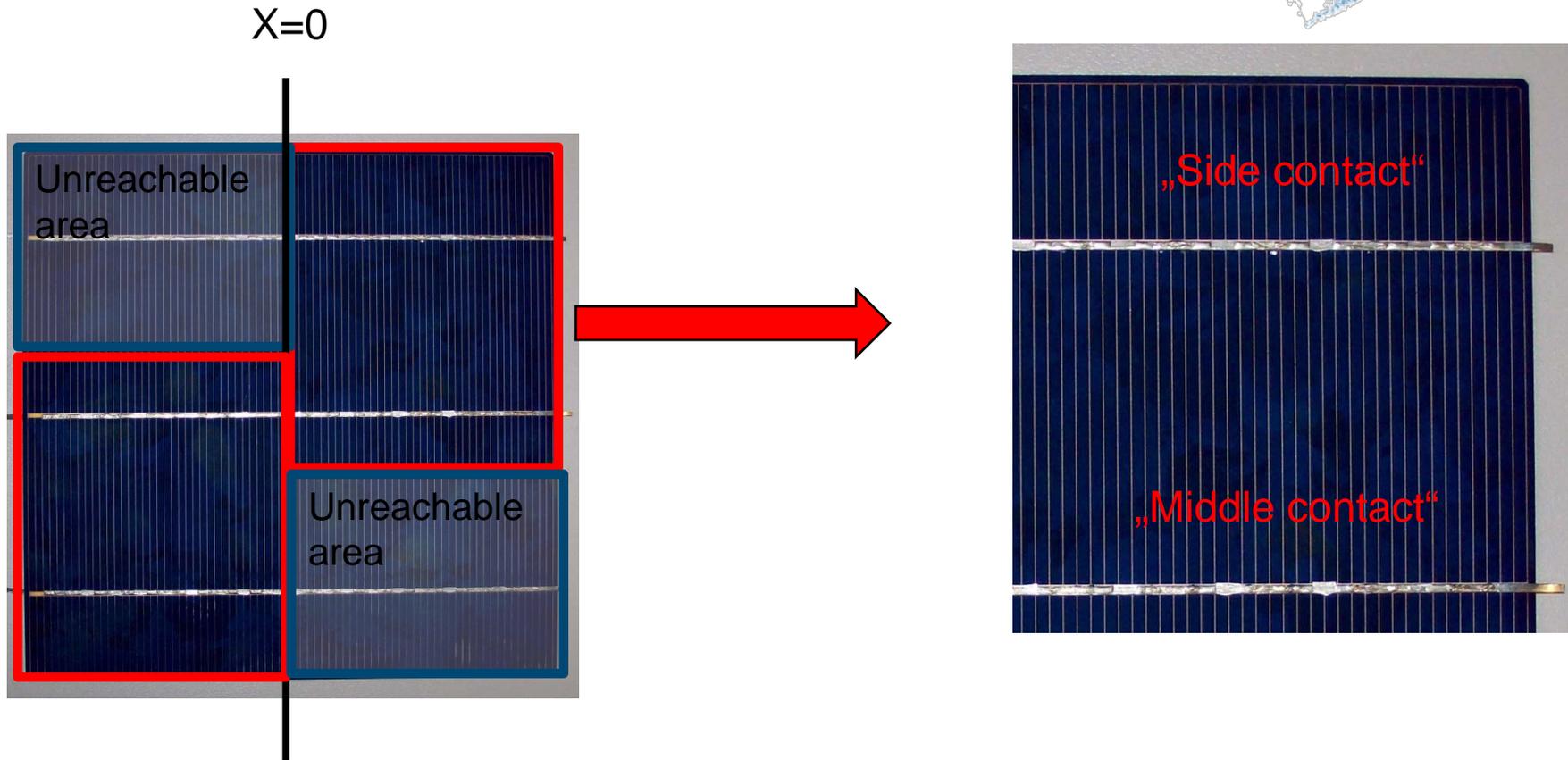
Stress measurement by XRD



- Empryrean system from Panalytical with Cu-X-ray tube
- Measurement of Cu lattice plane distance changes
- Goniometer scan at $2\Theta = 76^\circ$

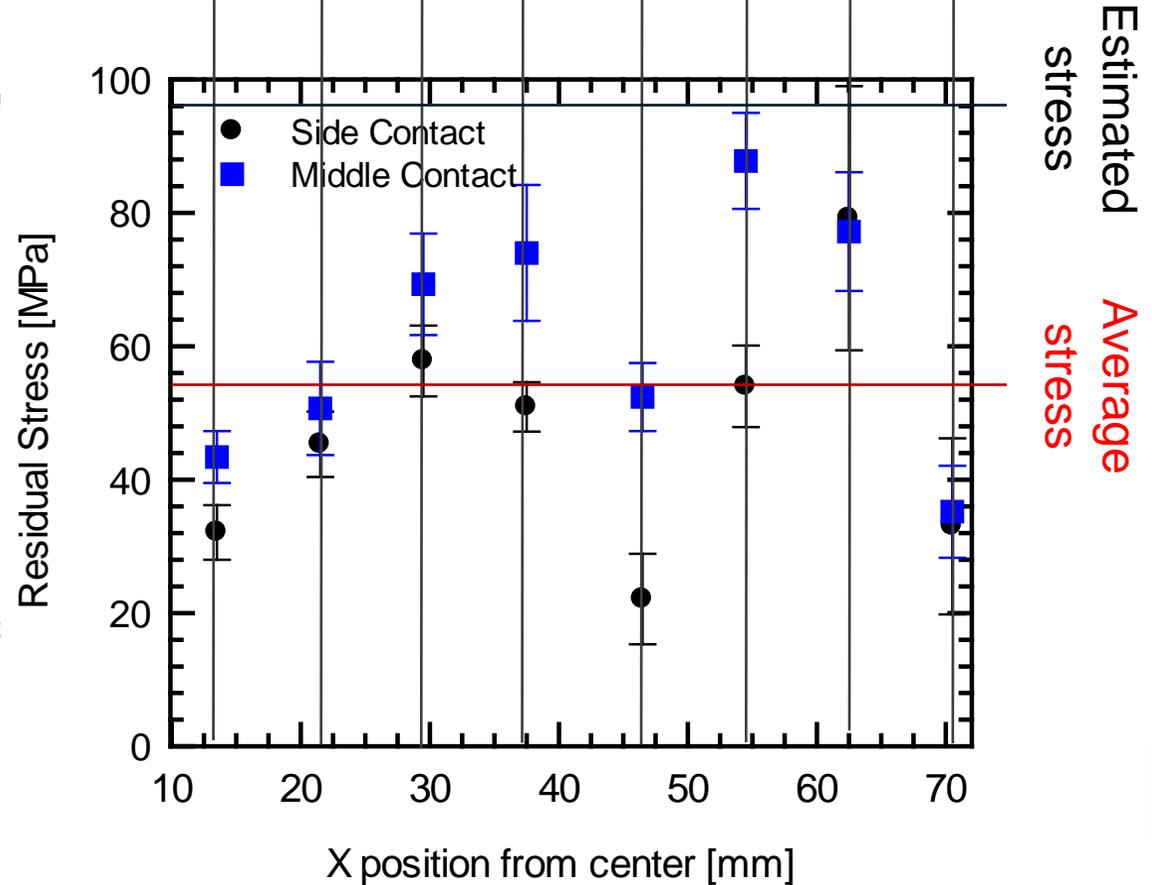
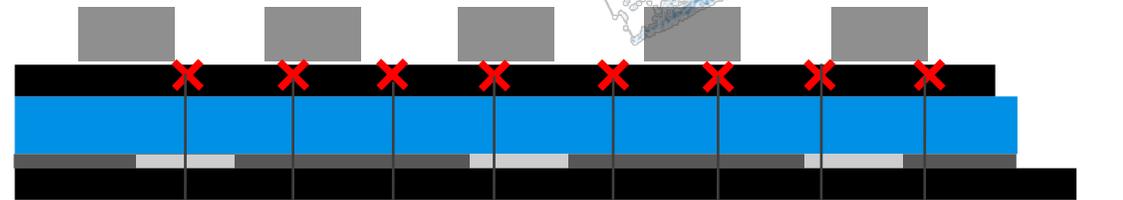
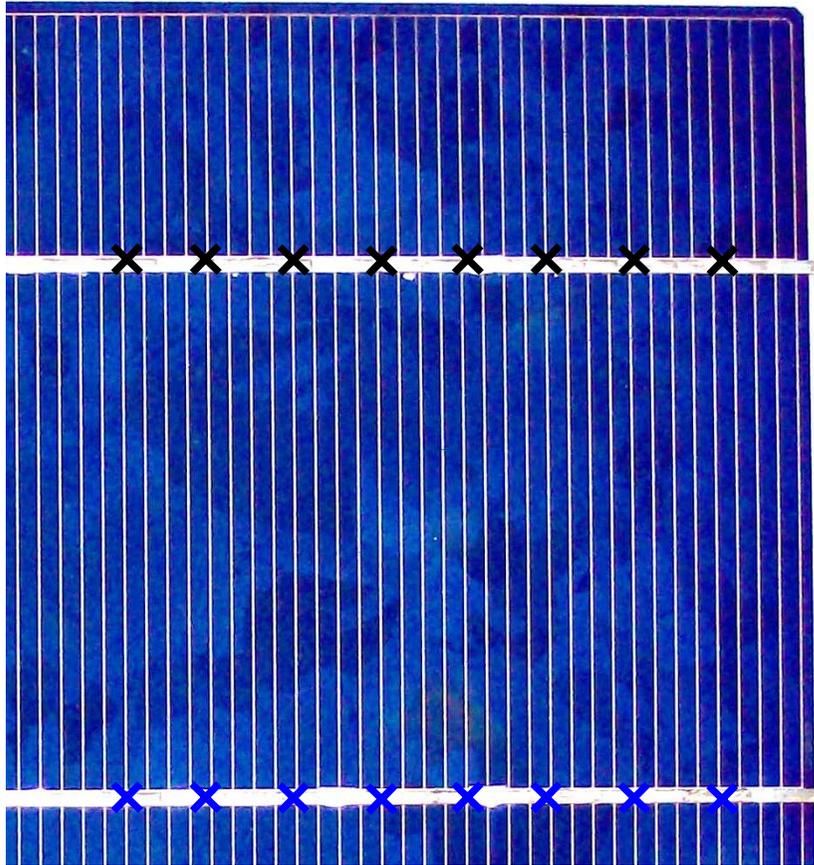
M. Birkholz, Thin film analysis by X-Ray scattering, Wiley-VCH Verlag, Weinheim, 2006.

Stress measurement in CIR

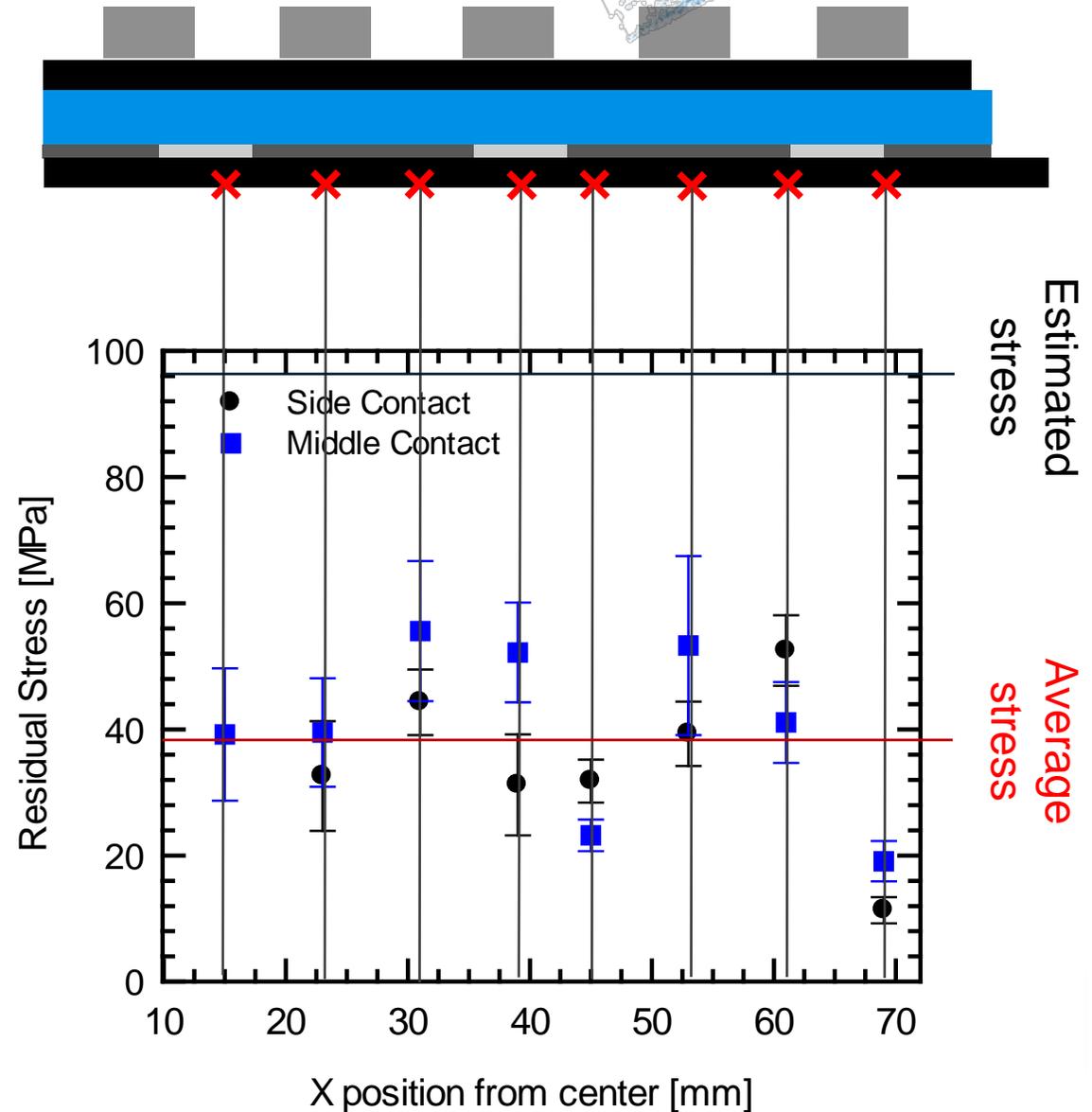
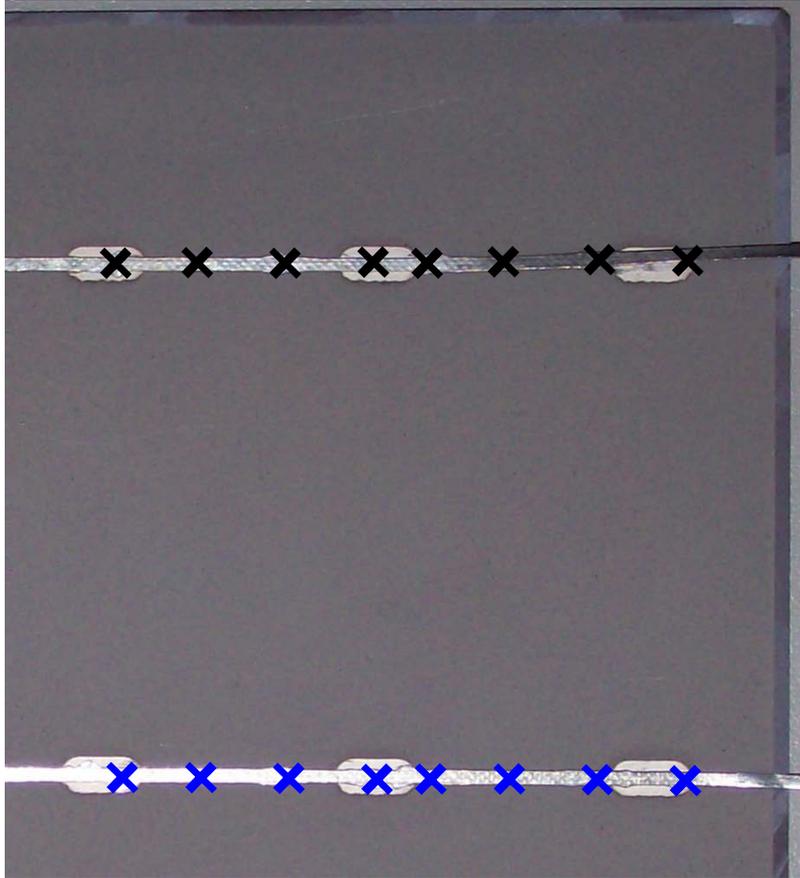


- Cell laid on a flat surface, without strain, 2.1 mm initial bow
- Spatially limited measurement due to sample holder geometry

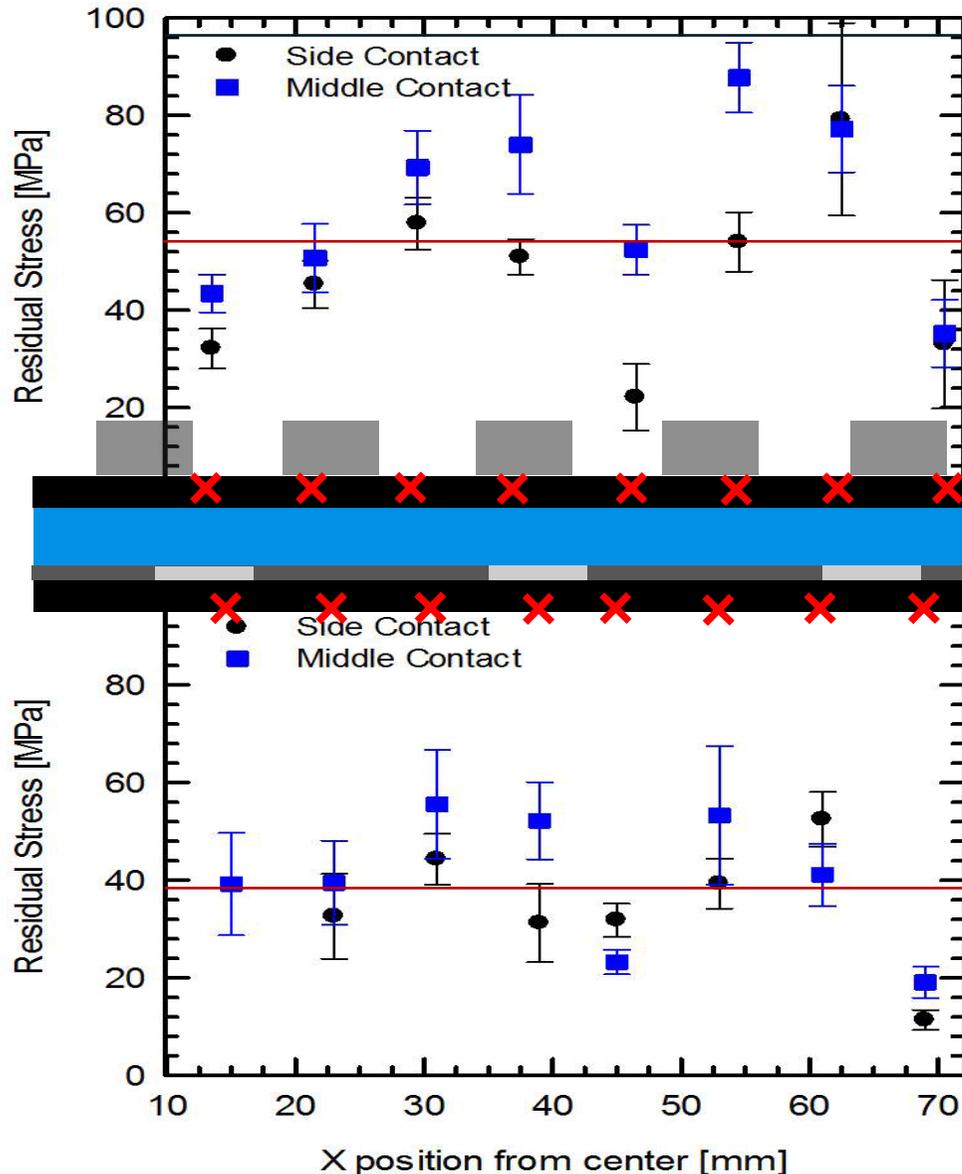
Front side stress



Rear side stress

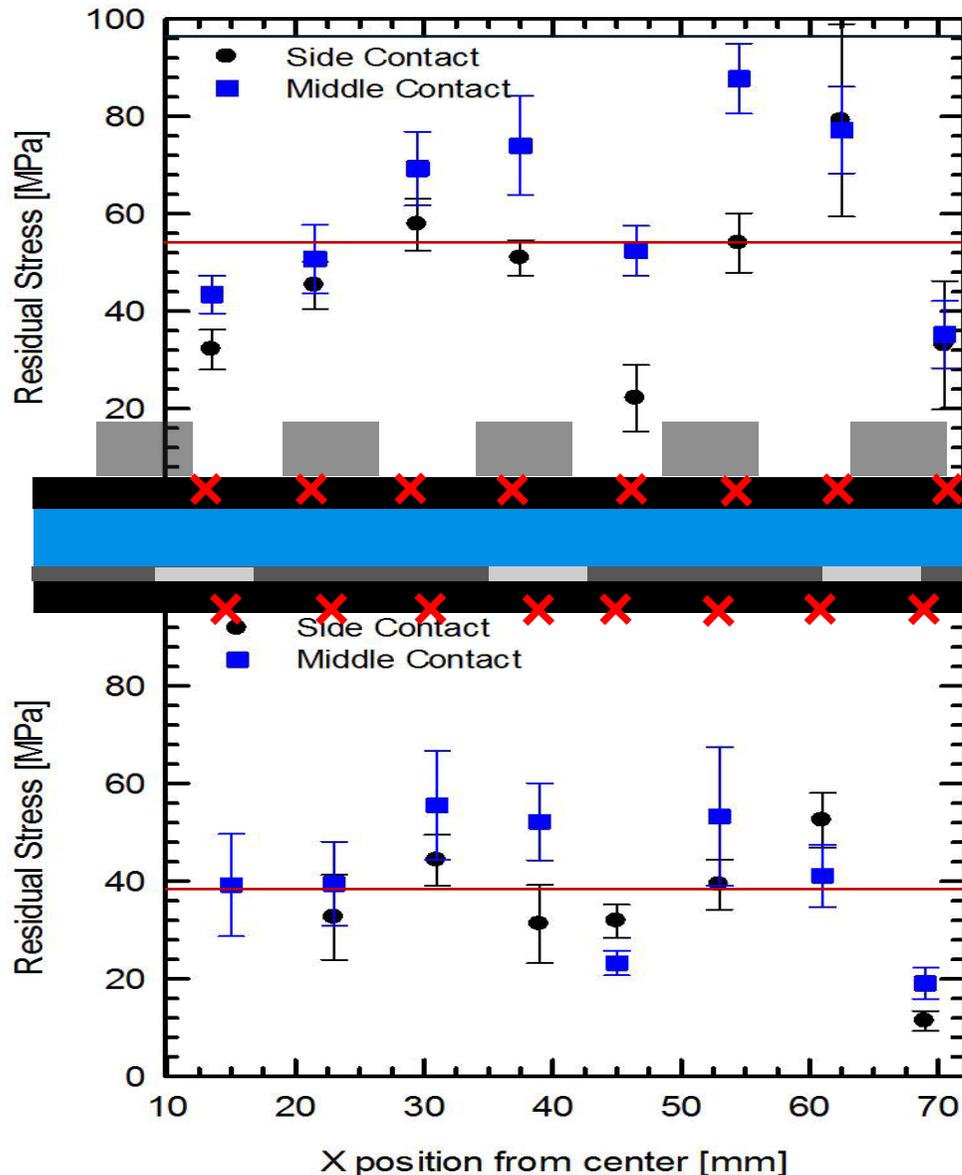


Stress comparison



- Maximum stresses fit to estimations
- Most measurements at about half of estimated stress (48 MPa)
- Similar stress pattern on all CIR on one cell
- Average rear side stress 16 MPa lower than front side stress
- Stress decrease at edge

Origin of stress pattern



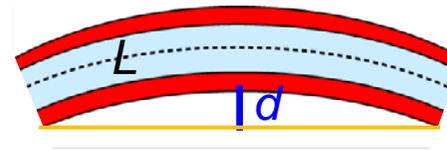
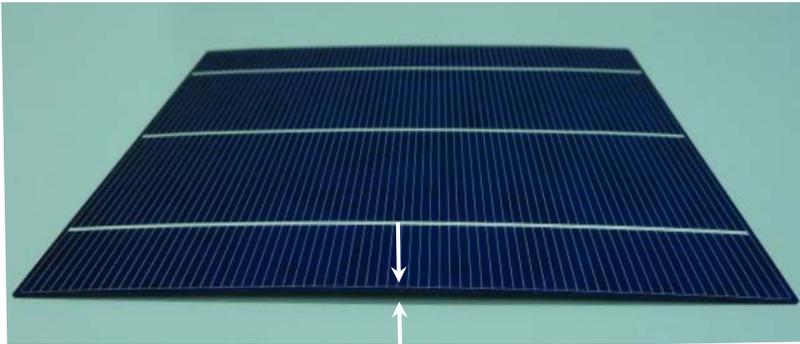
No correlation with:

- Solder head pattern
- Metallization pattern
- Thicknesses of materials
- Homogeneous material properties of CIR
- Initial bow → temperature profile

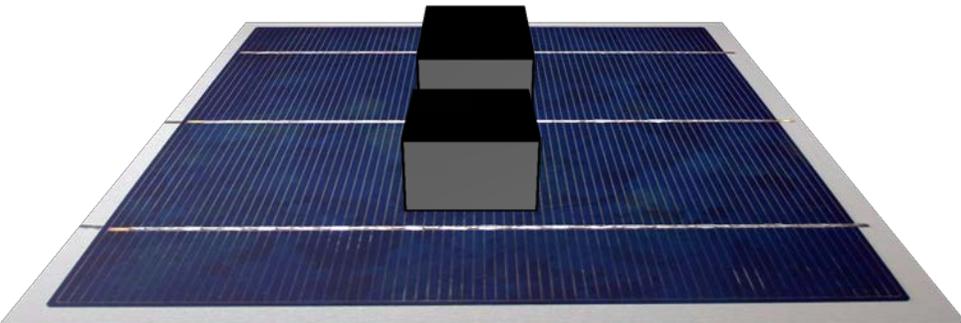
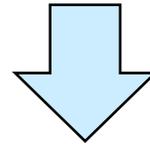
Flattening of solar cells similar to lamination process



Assumptions:



$$L = 156 \text{ mm}; d = 2.1 \text{ mm}$$
$$d_{\text{cell}} = 0.2 \text{ mm}; d_{\text{CIR}} = 0.15 \text{ mm}$$

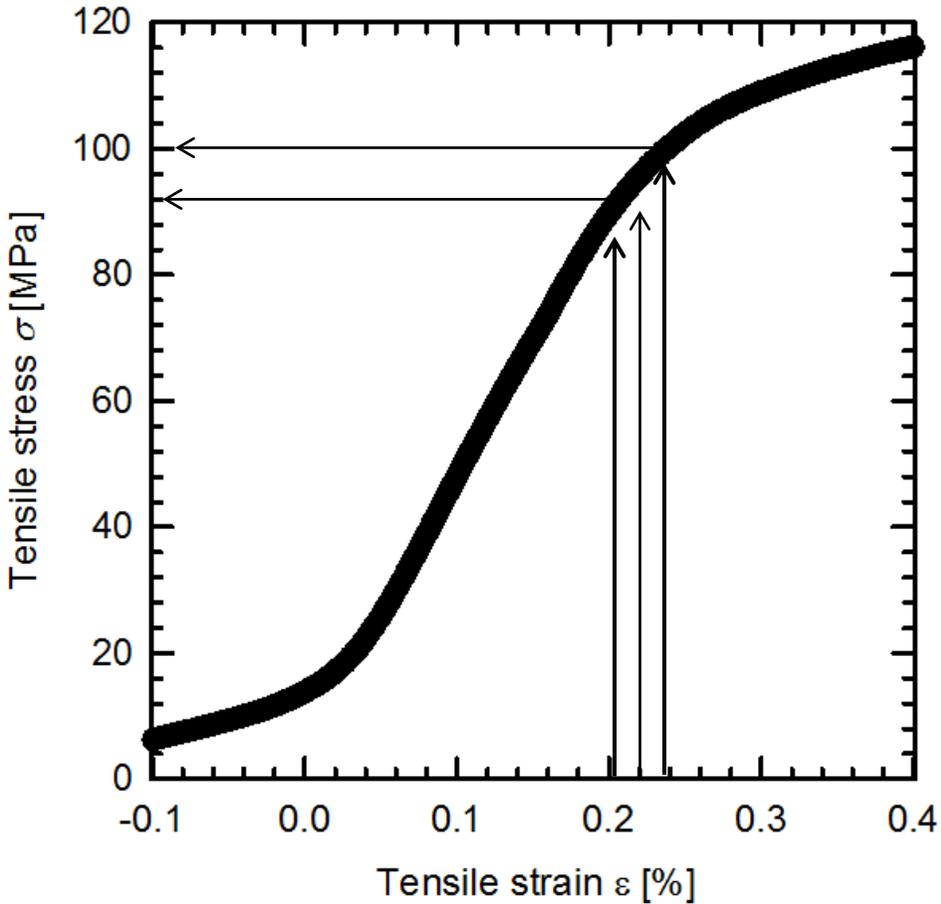
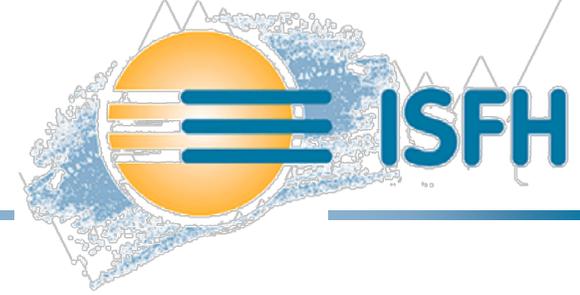


$$\Delta\varepsilon = -0.017 \%$$

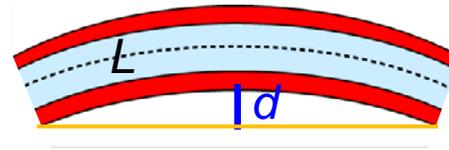


$$\Delta\varepsilon = +0.017 \%$$

Variation of stress in CIR



Assumptions:



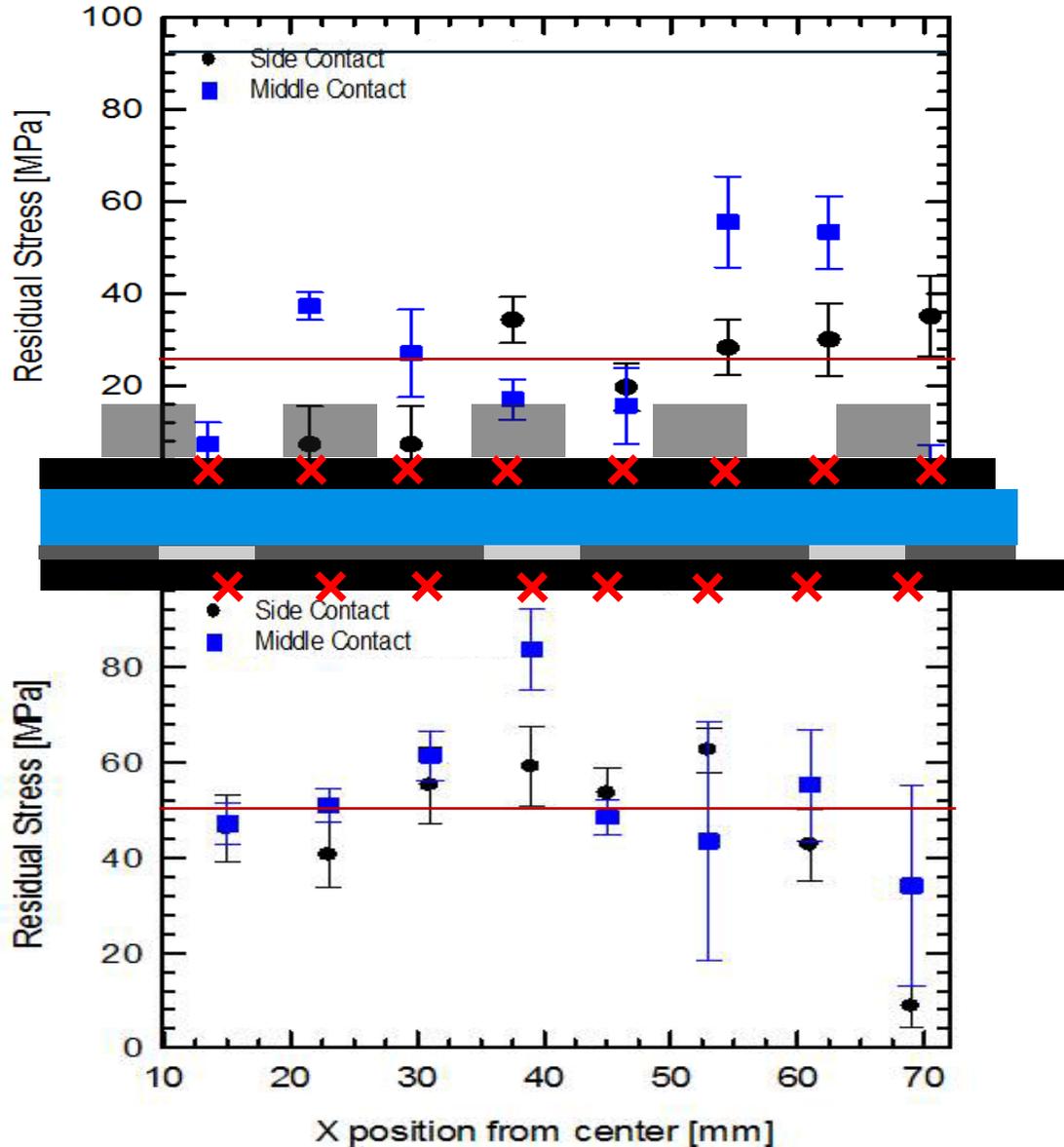
$$L = 156 \text{ mm}; d = 2.1 \text{ mm}$$
$$d_{cell} = 0.2 \text{ mm}; d_{CIR} = 0.15 \text{ mm}$$

$$\Delta\epsilon = -0.017 \%$$



$$\Delta\epsilon = +0.017 \%$$

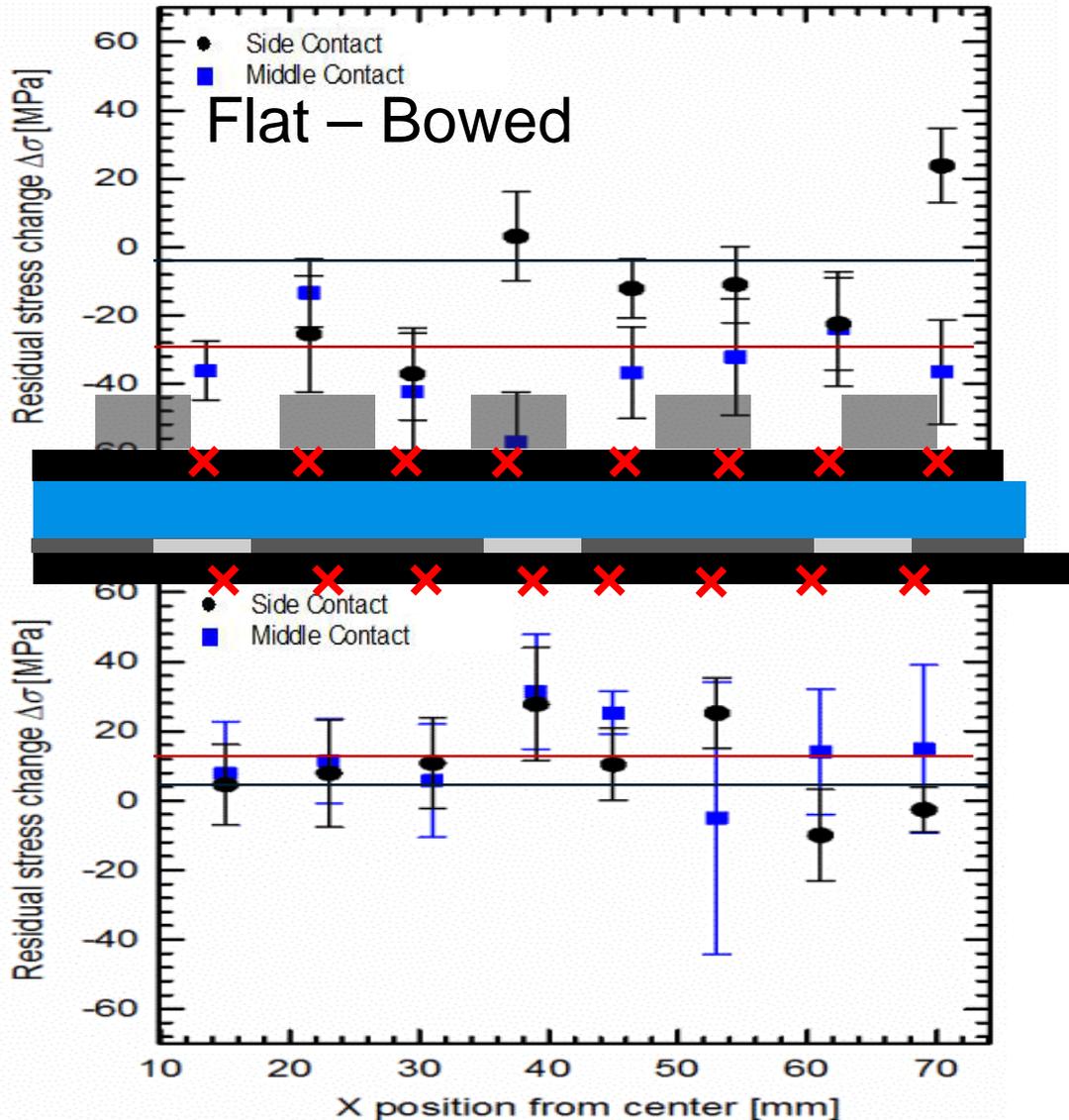
Stress in flattened solar cell



- Average front side stress is 25 MPa (67 MPa less than estimated)

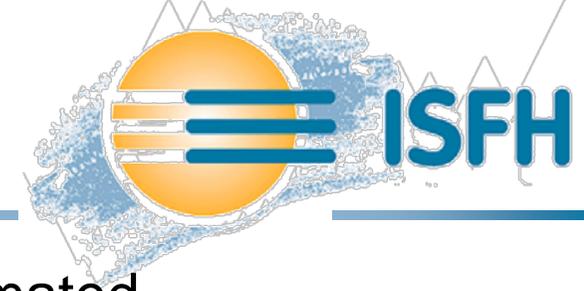
- Average rear side stress is 50 MPa (50 MPa less than estimated)

Stress variation in CIR due to flattening of solar cell



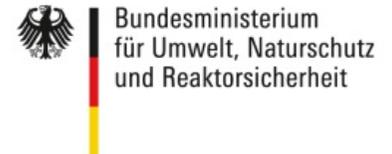
- Average front side stress decrease (29 MPa) one order of magnitude more than estimated (4 MPa)
- Average rear side stress increase (12 MPa) in order of magnitude to estimation (4 MPa)

Conclusion



- Maximum measured CIR stresses close to estimated stress of 96 Mpa, but in average about half of it → further relaxation processes
- Initially bowed: 16 MPa more stress at front side
- Flattened: 25 MPa more stress at rear side
- Stress decrease at front side higher than increase at rear side due to flattening
- Similar stress pattern on every CIR of one solar cell

Gefördert durch:



aufgrund eines Beschlusses
des Deutschen Bundestages

